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REAmend A #41
5-15-02 A

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BY:

Wm. S. Green

DATE:

April 3, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor : Barbara Vasquez et al.

Appl. No. : 10/062,942

Filed : January 31, 2002

Title : Method of Applying a Bottom Surface Protective Coating to a Wafer, and Wafer Dicing Method

P R E L I M I N A R Y A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

S i r :

Preliminary to examination, kindly amend the above-identified application as follows:

In the Specification:

Please replace the first paragraph on page 1, lines 8-18, with the following paragraph:

A The invention lies in the semiconductor processing technology field. More specifically, the present invention relates to a method for applying a protective coating to a bottom surface of a semiconductor wafer or to the bottom surface and all